

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S60	465	((Ti titanium metal) near (layer film)) with ((diffus\$3 Niv (nickel near vanadium)) with (((solder near wettable) Ni Au Gold Nickel) near (layer film))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 15:39
S61	129	((Ti titanium metal) near (layer film)) with ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) with (((solder near wettable) Ni Au Gold Nickel) near (layer film))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 16:24
S62	32	((Ti titanium metal) near (layer film)) near2 ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) near2 (((solder near wettable) Ni Au Gold Nickel) near (layer film))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:01
S63	7	("4040885"   "4842662"   "4893742"   "4917286"   "4927505"   "4950866"   "5110034").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/22 16:54
S64	0	(die chip) near2 ((Ti titanium metal) near (layer film)) near2 ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) near2 (((solder near wettable) Ni Au Gold Nickel) near (layer film)) near2 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:02
S65	0	(die chip) with ((Ti titanium metal) near (layer film)) near2 ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) near2 (((solder near wettable) Ni Au Gold Nickel) near (layer film)) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:03
S66	25	(die chip) and ((Ti titanium metal) near (layer film)) near2 ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) near2 (((solder near wettable) Ni Au Gold Nickel) near (layer film)) and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:08
S67	1	(die chip) with ((Ti titanium metal) near (layer film)) with ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) with (((solder near wettable) Ni Au Gold Nickel) near (layer film)) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:10
S68	5	(die chip) same ((Ti titanium metal) near (layer film)) same ((diffus\$3 Niv (nickel near vanadium)) near (layer film)) same (((solder near wettable) Ni Au Gold Nickel) near (layer film)) same substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/22 17:10